**FORM PTO-1595** 101000950

U.S. Department of Commerce

ΞT **Patent and Trademark Office** TI-22833 To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof. 1. Name of conveying party(ies): 2. Name and Address of receiving party(ies): Suan-Jong Jae Boon Name: TEXAS INSTRUMENTS INCORPORATED Jing Sua Goh Address: P.O. Box 655474, MS 3999 Dallas City: State: TX Zip: 75265 Additional name(s) & address(es) attached? \_\_\_\_Yes \_X\_No 3. Nature of Conveyance: X Assignment Merger Security Agreement Change of Name Other\_ Execution Date: February 3, 1999, February 11, 1999 4. Application number(s) or patent number(s). This document is being filed together with a new application. Execution date of the application: Title: REINFORCED SEMICONDUCTOR PACKAGE Docket No: TI-22833 A. Patent Application No.(s) B. Patent No.(s) S.N. Additional numbers attached? \_\_\_\_\_ Yes \_\_X\_ No Additional numbers attached? Yes \_\_X\_ No 5. Name and address of party to whom correspondence concerning 6. Number of applications and patents involved: \_\_ document should be mailed: Name: Jacquelline J. Garner Texas Instruments Incorporated Address: P.O. Box 655474, MS 3999 City: Dallas State: TX Zip: 75265 7. Amount of fee enclosed or authorized to be charged: \$40 04/05/1999 JSHABAZZ 00000003 200668 09167642 8. Deposit Account No: 20-0668 (Duplicate copies not required). 01 FC:581 40.00 CH DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Jacqueline J. Garner Reg. No.36,144

WHEREAS, the or each below named inventor (hereinafter INVENTOR) is the or an inventor of an invention for which a U.S. patent application has been filed as set forth below, and made the said invention in the course of employment by TEXAS INSTRUMENTS SINGAPORE (PTE) Limited, a company organized of according to the laws of Singapore, having an office at #07-00 Shell House, United Engineers Square, 83 Clemenceau Avenue, Singapore 239920, hereinafter (TIS);

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with its principal office at 7839 Churchill Way, MS 3999, Dallas, Texas 75251, is desirous of acquiring our entire right, title interest in and to the said invention outside of Singapore, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, by this Assignment, effective as of <u>June 18, 1998</u>, TIS and INVENTOR sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, the entire right, title and interest in and to the said invention in the U.S.A. and in all other countries outside Singapore; in and to the U.S. patent application as identified below and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and to file applications and obtain patents in its own name in any said other country or group of countries, and to claim priority under the terms of the International Convention for the Protection of Industrial Property or any other relevant convention;

TIS and INVENTOR hereby authorize and request the Commissioner of Patents to issue all U.S. patents for said invention, or patents resulting therefrom, insofar as our interest is concerned to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of the entire right, title and interest.

TIS and INVENTOR further agree to communicate to TEXAS INSTRUMENTS INCORPORATED or to its successors, assigns and legal representatives, any facts known to them respecting the said invention, and at the expense of TEXAS INSTRUMENTS INCORPORATED, sign any and all patent applications, assignments, affidavits and other lawful papers, execute all applications, make all lawful oaths, testify in any legal or quasi-legal proceedings and generally everything possible to said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries outside Singapore.

Assignment TI-22833 Page 3/3

Name:

Jing Sua Goh

Signature:

Address:

113 Hillview Cresent

Singapore 669506

11 + Feb 99

Date:

Address:

Date:

Title of Invention: REINFORCED SEMICONDUCTOR PACKAGE Inventor(s): Suan-Jong Jae Boon, Jing Sua Goh U.S. Application Serial No: 09/167,642 Filed: October 6, 1998 IN WITNESS WHEREOF, this Agreement has been executed as set forth below: Signed at: by Texas Instruments Singapore (PTE) Limited Name: Larry Tan Jwee Meng Title: VP, Asia Marketing & Sales/Singapore Managing Director Date: February 22, 1999 Witness: and by the INVENTOR(S): Suan-Jong Jae Boon Name: Signature:

271-A Jalan Kayu

Singapore 799499

**RECORDED: 03/29/1999** 

3rd Feb 1999